

TI DESIGNS

IPD152: Hardware-Compensated Ratiometric 3-Wire RTD System, 0C-100C, 0.005C Error

Item #	Quantity	Designator	Value	Description	Manufacturer	Part Number
1	8	C1, C4, C5, C7, C9, C10, C11, C13	0.1 μF	CAP CER 0.1UF 50V 10% X7R 0603	MuRata	GRM188R71H104KA93D
2	2	C2, C8	10 μF	CAP CER 10UF 25V 20% X7R 1210	ТDК	C3225X7R1E106M250AC
3	2	C3, C6	0.01 μF	CAP CER 10000PF 25V 5% NP0 0603	ток	C1608C0G1E103J080AA
4	1	C12	1 μF	CAP CER 1UF 25V 10% X7R 0603	Taiyo Yuden	ТМК107В7105КА-Т
5	2	C14, C16	3300 pF	CAP CER 3300PF 25V 5% NP0 0603	Samsung Electro-Mech	CL10C332JA8NNNC
6	1	C15	0.033 μF	CAP CER 0.033UF 25V 5% NP0 0805	ток	C2012C0G1E333J125AA
7	2	C17, C19	1500 pF	CAP CER 1500PF 25V 5% NP0 0603	MuRata	GRM1885C1E152JA01D
8	1	C18	0.015 μF	CAP CER 0.015UF 25V 5% NP0 0603	Kemet	C0603C153J3GACTU
9	2	FB1, FB2		FERRITE CHIP 600 OHM 200MA 0603	MuRata	BLM18HG601SN1D
10	1	J1		CONN HEADER 3POS .100" SGL GOLD	Samtec, Inc.	TSW-103-07-G-S
11	1	J2		CONN SOCKET 50PIN .050 R/A SNGL	Mill-Max Manufacturing Corp.	851-43-050-20-001000
12	1	.13		TERMINAL BLOCK 3.5MM 3POS PCB	On Shore Technology Inc	ED555/3DS
13	1	R1	140 k	RES 140K OHM 1/10W 1% 0603 SMD	Vishay Dale	CRCW0603140KFKEA
14	1	R2	78.7 k	RES 78.7K OHM 1/10W 1% 0603 SMD	Vishay Dale	CRCW060378K7FKEA
15	2	R3, R4	0	RES 0.0 OHM 1/10W JUMP 0603 SMD	Panasonic Electronic	ERJ-3GEY0R00V
16	2	R5, R7	10 k	RES, 10.0k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-0710KL
17	2	R8, R10	20 k	RES, 20.0k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-0720KL
18		R6	120	RES 120 OHM 1/10W .02% 0603	Susumu	RG1608V-121-P-T1
19	1	R9	3.3 k	RES 3.3K OHM 0.1W 0.01% 0805	Susumu	RG2012L-332-L-T05
20	1	.TP1		Test Point, TH, Compact, Red	Keystone	5005
21	1	TP2		Test Point, TH, Compact, Black	Keystone	5006
22	1	U1		IC REG LDO ADJ 0.15A 8MSO	Texas Instruments Inc	TPS7A4901DGNR
23	1	U2		IC 4BIT NON-INV TRANSLTR 14TSSOP	Texas Instruments Inc	TXS0104EPWR
24	1	U3		IC ADC 24BIT DEL/SIG LN 20TSSOP	Texas Instruments Inc	ADS1247IPW

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